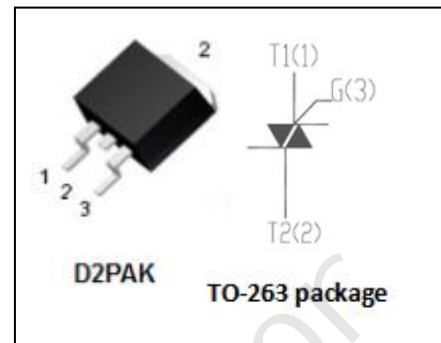


**FEATURES**

- With D2PAK package.
- Glass passivated triacs in a plastic envelope, for use in applications requiring high bidirectional transient and blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.
- Minimum Lot-to-Lot variations for robust device performance and reliable operation.

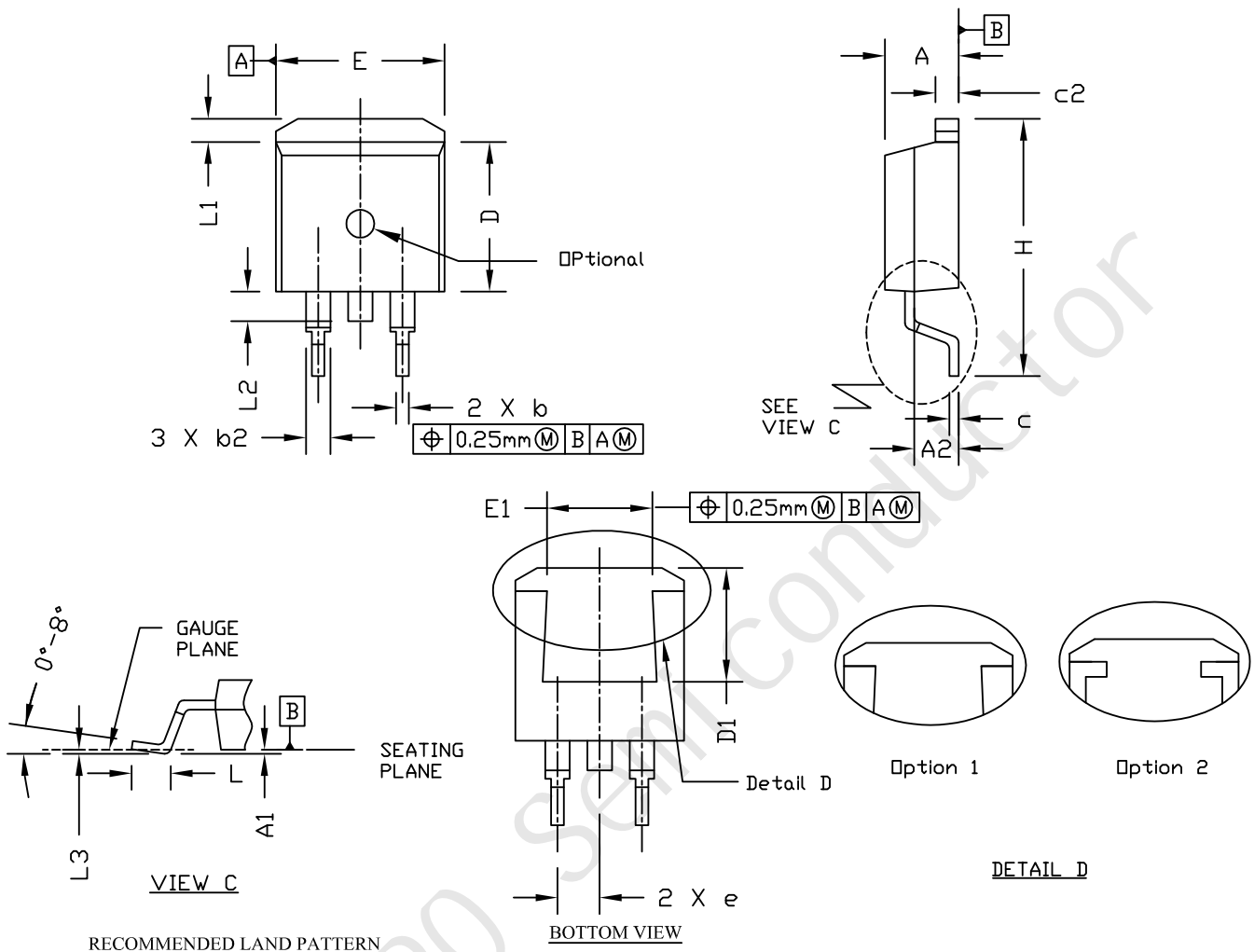

**ABSOLUTE MAXIMUM RATINGS(Ta=25°C)**

SYMBOL	PARAMETER	MIN	UNIT
V <sub>DRM</sub>	Repetitive peak off-state voltage	800	V
V <sub>RRM</sub>	Repetitive peak off-state voltage	800	V
I <sub>T(RMS)</sub>	RMS on-state current (full sine wave)	16	A
I <sub>TSM</sub>	Non-repetitive peak on-state current t <sub>p</sub> =20ms	160	A
P <sub>GM</sub>	Peak gate power dissipation	5	W
P <sub>G(AV)</sub>	Average gate power dissipation	0.5	W
T <sub>j</sub>	Operating junction temperature	125	°C
T <sub>stg</sub>	Storage temperature	-40~150	°C

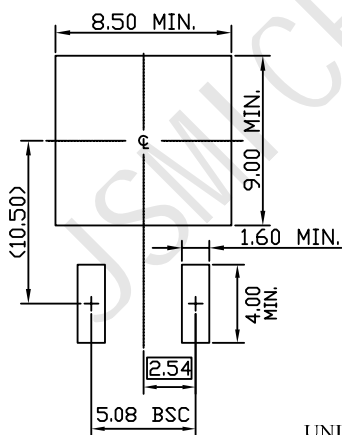
**ELECTRICAL CHARACTERISTICS (T<sub>c</sub>=25°C unless otherwise specified)**

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT	
I <sub>RRM</sub>	Repetitive peak reverse current	V <sub>R</sub> =V <sub>RRM</sub> , V <sub>R</sub> =V <sub>RRM</sub> , T <sub>J</sub> =125°C		0.02 0.5	mA	
I <sub>DRM</sub>	Repetitive peak off-state current	V <sub>D</sub> =V <sub>DRM</sub> , V <sub>D</sub> =V <sub>DRM</sub> , T <sub>J</sub> =125°C		0.02 0.5	mA	
I <sub>GT</sub>	Gate trigger current	V <sub>D</sub> =12V; I <sub>T</sub> = 0.1A		I	50	mA
				II	50	
				III	50	
				IV	100	
V <sub>GT</sub>	Gate trigger voltage	V <sub>D</sub> =12V; I <sub>T</sub> = 0.1A		1.5	V	
V <sub>TM</sub>	On-state voltage	I <sub>T</sub> = 20A		1.6	V	
I <sub>H</sub>	Holding current	I <sub>GT</sub> = 0.1A, V <sub>D</sub> = 12V		30	mA	

TO263(D2PAK) PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



UNIT: mm

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.064	4.45	4.826	0.160	0.175	0.190
A1	0.00	---	0.254	0.000	---	0.010
A2	2.20	2.67	2.90	0.087	0.105	0.114
b	0.508	0.81	0.991	0.020	0.032	0.039
b2	1.143	1.27	1.778	0.045	0.050	0.070
c	0.381	0.50	0.737	0.015	0.020	0.029
c2	1.143	1.27	1.651	0.045	0.050	0.065
D	8.382	9.14	9.652	0.330	0.360	0.380
D1	6.858	8.00	8.37	0.270	0.315	0.330
e	2.54 BSC			0.100 BSC.		
E	9.652	10.03	10.668	0.380	0.395	0.420
E1	6.223	8.00	8.37	0.245	0.315	0.330
H	14.605	15.24	15.875	0.575	0.600	0.625
L	1.778	2.54	2.794	0.070	0.100	0.110
L1	1.02	1.27	1.676	0.040	0.050	0.066
L2	1.27	1.52	1.778	0.50	0.60	0.070
L3	0.25 BSC			0.010 BSC.		

NOTE:

1. PACKAGE BODY SIDES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH SHOULD BE LESS THAN 6 MILS.
2. TOLERANCE 0.10 MILLIMETERS UNLESS OTHERWISE SPECIFIED.
3. DIMENSION L IS MEASURED IN GAUGE LINE.
4. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
5. REFER TO JEDEC TO-263 AB.

单击下面可查看定价，库存，交付和生命周期等信息

[>>JSMSEMI\(杰盛微\)](#)